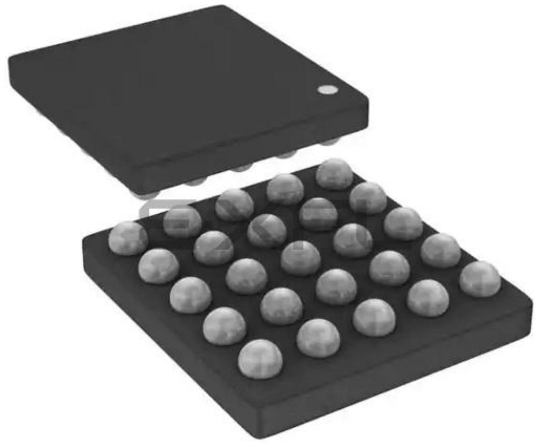

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, Cap Sense, LCD, LVD, POR, PWM, SmartSense, WDT
Number of I/O	21
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	25-UFBGA, WLCSP
Supplier Device Package	25-WLCSP (2.07×2.11)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4246fni-ds402t

More Information

Cypress provides a wealth of data at www.cypress.com to help you to select the right PSoC device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources, see the knowledge base article KBA86521, How to Design with PSoC 3, PSoC 4, and PSoC 5LP. Following is an abbreviated list for PSoC 4:

- Overview: PSoC Portfolio, PSoC Roadmap
- Product Selectors: PSoC 1, PSoC 3, PSoC 4, PSoC 5LP
  In addition, PSoC Creator includes a device selection tool.
- Application notes: Cypress offers a large number of PSoC application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with PSoC 4 are:
  - AN79953: Getting Started With PSoC 4
  - AN88619: PSoC 4 Hardware Design Considerations
  - AN86439: Using PSoC 4 GPIO Pins
  - AN57821: Mixed Signal Circuit Board Layout
  - AN81623: Digital Design Best Practices
  - AN73854: Introduction To Bootloaders
  - AN89610: ARM Cortex Code Optimization
- Technical Reference Manual (TRM) is in two documents:
  - Architecture TRM details each PSoC 4 functional block.
  - Registers TRM describes each of the PSoC 4 registers.
- Development Kits:
  - CY8CKIT-042, PSoC 4 Pioneer Kit, is an easy-to-use and inexpensive development platform. This kit includes connectors for Arduino™ compatible shields and Digilent® Pmod™ daughter cards.
  - CY8CKIT-049 is a very low-cost prototyping platform. It is a low-cost alternative to sampling PSoC 4 devices.
  - CY8CKIT-001 is a common development platform for any one of the PSoC 1, PSoC 3, PSoC 4, or PSoC 5LP families of devices.

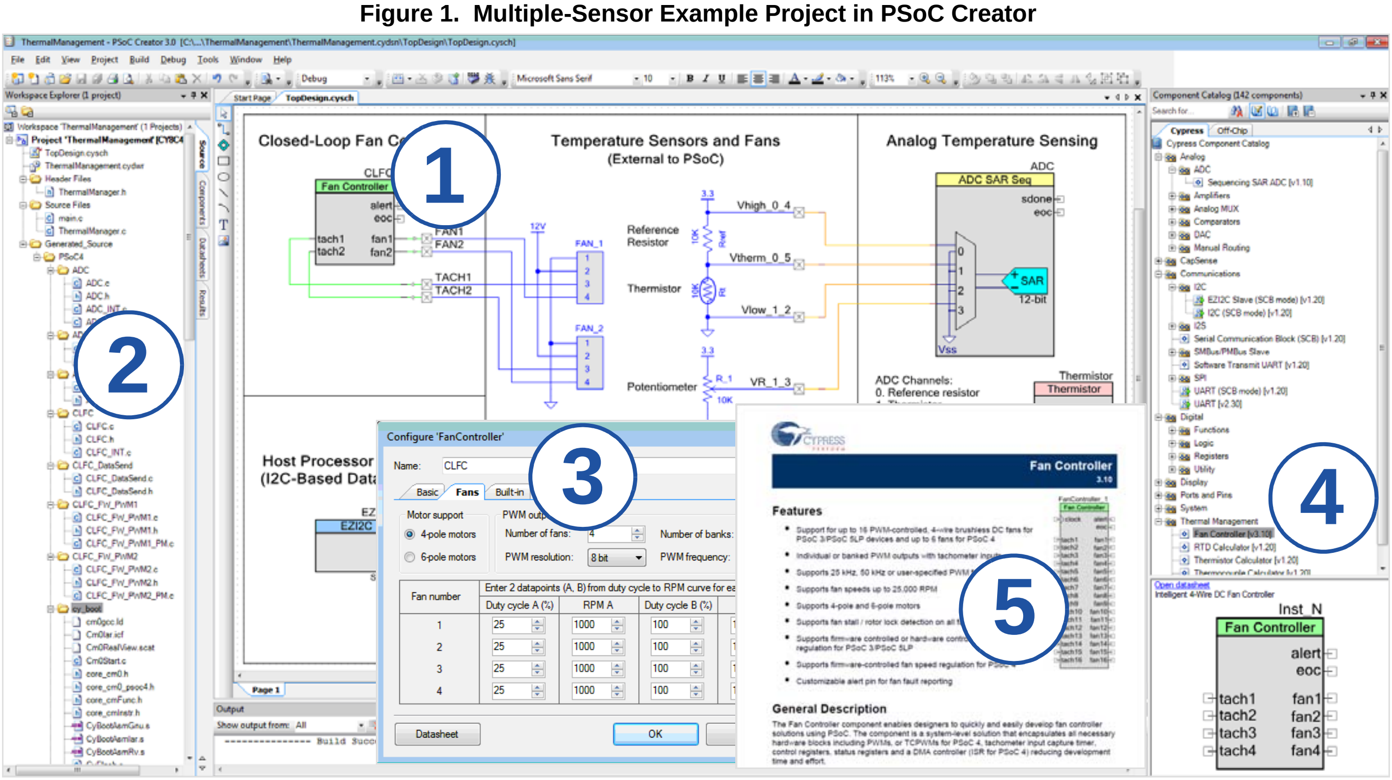
The MiniProg3 device provides an interface for flash programming and debug.

PSoC Creator

PSoC Creator is a free Windows-based Integrated Design Environment (IDE). It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, and PSoC 5LP based systems. Create designs using classic, familiar schematic capture supported by over 100 pre-verified, production-ready PSoC Components; see the list of component datasheets. With PSoC Creator, you can:

1. Drag and drop component icons to build your hardware system design in the main design workspace
2. Codesign your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
3. Configure components using the configuration tools
4. Explore the library of 100+ components
5. Review component datasheets

Figure 1. Multiple-Sensor Example Project in PSoC Creator



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Functional Definition

CPU and Memory Subsystem

CPU

The Cortex-M0 CPU in the PSoC 4200DS is part of the 32-bit MCU subsystem, which is optimized for low-power operation with extensive clock gating. Most instructions are 16 bits in length and execute a subset of the Thumb-2 instruction set. The Cypress implementation includes a hardware multiplier that provides a 32-bit result in one cycle. It includes a nested vectored interrupt controller (NVIC) block with 32 interrupt inputs and also includes a Wakeup Interrupt Controller (WIC), which can wake the processor up from the Deep Sleep mode allowing power to be switched off to the main processor when the chip is in the Deep Sleep mode. The Cortex-M0 CPU provides a Non-Maskable Interrupt (NMI) input, which is made available to the user when it is not in use for system functions requested by the user.

The CPU also includes a debug interface, the serial wire debug (SWD) interface, which is a 2-wire form of JTAG; the debug configuration used for PSoC 4200DS has four break-point (address) comparators and two watchpoint (data) comparators.

Flash

The PSoC 4200DS has a flash module with a flash accelerator, tightly coupled to the CPU to improve average access times from the flash block. The flash accelerator delivers 85% of single-cycle SRAM access performance on average. Part of the flash module can be used to emulate EEPROM operation if required.

SRAM

8K of SRAM memory is provided.

SROM

A supervisory ROM that contains boot and configuration routines is provided.

DMA

A DMA engine, with eight channels, is provided that can do 32-bit transfers and has chainable ping-pong descriptors.

System Resources

Power System

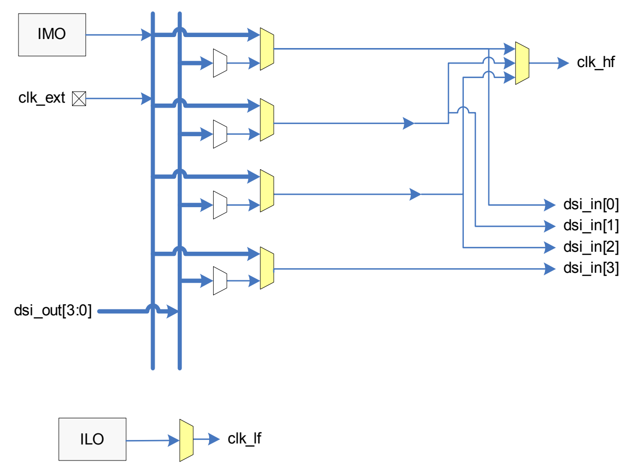
The power system is described in detail in the section Power on page 10. It provides assurance that voltage levels are as required for each respective mode and either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (brown-out detect (BOD)) or interrupts (low-voltage detect (LVD)). The PSoC 4200D operates with a single external supply over the range of 1.71 V to 5.5 V and has three different power modes, transitions between which are managed by the power system. The PSoC 4200D provides Active, Sleep, and Deep Sleep modes.

Clock System

The PSoC 4200DS clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that no meta-stable conditions occur.

The clock system for the PSoC 4200DS consists of the IMO (3 to 48 MHz) and the ILO (40-kHz nominal) internal oscillators, and provision for an external clock.

Figure 2. PSoC 4200DS MCU Clocking Architecture



The clk_hf signal can be divided down to generate synchronous clocks for the UDBs, and the analog and digital peripherals. There are a total of six clock dividers for the PSoC 4200DS, each with 16-bit divide capability, two of which support fractional baud-rate generation. The 16-bit capability allows a lot of flexibility in generating fine-grained frequency values and is fully supported in PSoC Creator.

IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4200D. It is trimmed during testing to achieve the specified accuracy. Trim values are stored in nonvolatile memory. Trimming can also be done on the fly to allow in-field calibration. The IMO default frequency is 24 MHz and it can be adjusted between the range of 24 to 48 MHz. IMO tolerance with Cypress-provided calibration settings is ±2%. An IMO post-divider with possible divide values of 2, 4, or 8 can be used to divide the clock down to 3 MHz if required.

ILO Clock Source

The ILO is a very low power oscillator, nominally 40 kHz, which is primarily used to generate clocks for peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

Watchdog Timer

A watchdog timer is implemented in the clock block running from the low-frequency clock; this allows watchdog operation during Deep Sleep and generates a watchdog reset or an interrupt if not serviced before the timeout occurs. The watchdog reset is recorded in the Reset Cause register.

Reset

The PSoC 4200DS can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset to avoid complications with configuration and multiple pin functions during power-on or reconfiguration.

Analog Block

Low-power Comparators

The PSoC 4200DS has a pair of low-power comparators, with two different power modes allowing trade-off of power versus response time.

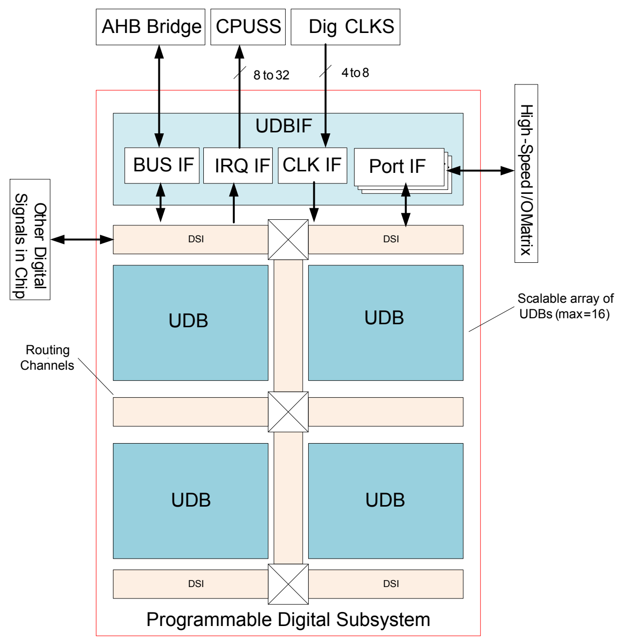
Programmable Digital

Universal Digital Blocks (UDBs) and Port Interfaces

The PSoC 4200DS has four UDBs; the UDB array also provides a switched Digital System Interconnect (DSI) fabric that allows signals from peripherals and ports to be routed to and through the UDBs for communication and control. The UDB array is shown in the following figure.

UDBs can be clocked from a clock divider block, from a port interface (required for peripherals such as SPI), and from the DSI network directly or after synchronization.

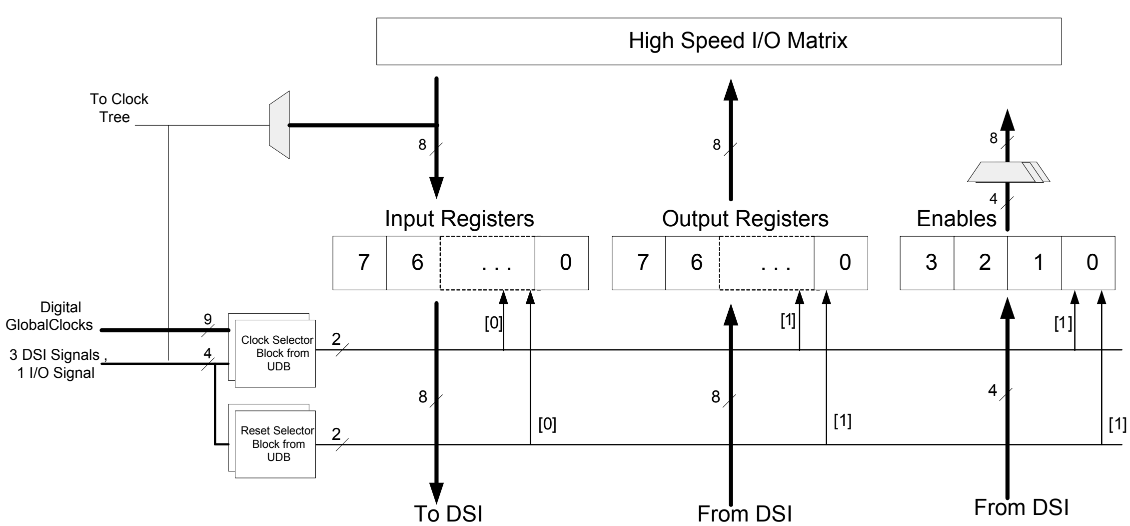
Figure 3. UDB Array



A port interface is defined, which acts as a register that can be clocked with the same source as the PLDs inside the UDB array. This allows faster operation because the inputs and outputs can be registered at the port interface close to the I/O pins and at the edge of the array. The port interface registers can be clocked by one of the I/Os from the same port. This allows interfaces such as SPI to operate at higher clock speeds by eliminating the delay for the port input to be routed over DSI and used to register other inputs. The port interface is shown in Figure 4.

The UDBs can generate interrupts (one UDB at a time) to the interrupt controller. The UDBs retain the ability to connect to any pin on the chip through the DSI.

Figure 4. Port Interface



Pinouts

The following is the pin list for the PSoC 4200DS. Pins 16, 17, and 18 are No-Connects in the 28-pin SSOP package.

Table 1. PSoC 4200DS Pin Description

28-Pin SSOP		25-Ball CSP		Alternate Functions for Pins						Pin Description
Pin	Name	Pin	Name	Analog	PRGIO	Alt 1	Alt 2	Alt 3	Alt 4	
19	P0.0	E4	P0.0	lpcomp.in_p[0]		tcpwm.line[2]			scb[0].spi_select1	P0.0, LPC0, TCPWM2, SCB0
20	P0.1	E3	P0.1	lpcomp.in_n[0]		tcpwm.line_compl[2]			scb[0].spi_select2	P0.1, LPC0, TCPWM2, SCB0
21	P0.2	D3	P0.2			tcpwm.line[3]			scb[0].spi_select3	P0.2, TCPWM3, SCB0
22	P0.4	E2	P0.4				scb[1].uart_rx	scb[1].i2c_scl	scb[1].spi_mosi	P0.4, SCB1
23	P0.5	C4	P0.5				scb[1].uart_tx	scb[1].i2c_sda	scb[1].spi_miso	P0.5, SCB1
24	P0.6	C3	P0.6			ext_clk	scb[1].uart_cts		scb[1].spi_clk	P0.6, Ext Clock, SCB1
25	XRES	D2	XRES							XRES
26	VCCD	E1	VCCD							Regulator Output
28	VSSD	D1	VSSD							Power Supply
27	VDDD	C1	VDDD							Ground
1	P1.0	C2	P1.0			tcpwm.line[2]	scb[0].uart_rx	scb[0].i2c_scl	scb[0].spi_mosi	P1.0, TCPWM2, SCB0
2	P1.1	B2	P1.1			tcpwm.line_compl[2]	scb[0].uart_tx	scb[0].i2c_sda	scb[0].spi_miso	P1.1, TCPWM2, SCB0
3	P1.2	B1	P1.2			tcpwm.line[3]	scb[0].uart_cts		scb[0].spi_clk	P1.2, TCPWM3, SCB0
4	P1.3	A1	P1.3			tcpwm.line_compl[3]	scb[0].uart_rts		scb[0].spi_select0	P1.3, TCPWM3, SCB0
5	P2.2	B3	P2.2		prgio[0].io[2]		scb[2].uart_rx	scb[2].i2c_scl	scb[2].spi_mosi	P2.2, PRG, SCB2
6	P2.3	A2	P2.3		prgio[0].io[3]		scb[2].uart_tx	scb[2].i2c_sda	scb[2].spi_miso	P2.3, PRG. SCB2
7	P2.4	B4	P2.4		prgio[0].io[4]	tcpwm.line[0]	scb[2].uart_cts	lpcomp.comp[0]	scb[2].spi_clk	P2.4, PRG, TCPWM0, SCB2, LPC0
8	P2.5	A4	P2.5		prgio[0].io[5]	tcpwm.line_compl[0]	scb[2].uart_rts		scb[2].spi_select0	P2.5, PRG, TCPWM0, SCB2
9	P2.6	A3	P2.6		prgio[0].io[6]	tcpwm.line[1]			scb[2].spi_select1	P2.6, PRG, TCPWM1, SCB2
10	P2.7	A5	P2.7		prgio[0].io[7]	tcpwm.line_compl[1]			scb[2].spi_select2	P2.7, PRG, TCPWM1, SCB2

Table 1. PSoC 4200DS Pin Description *(continued)*

28-Pin SSOP		25-Ball CSP		Alternate Functions for Pins						Pin Description
Pin	**Name**	**Pin**	**Name**	**Analog**	**PRGIO**	**Alt 1**	**Alt 2**	**Alt 3**	**Alt 4**	
11	P3.0	D5	P3.0			tcpwm.line[0]	scb[1].uart_rx	scb[1].i2c_scl	scb[1].spi_mosi	P3.0, TCPWM0, SCB1
12	P3.1	C5	P3.1			tcpwm.line_compl[0]	scb[1].uart_tx	scb[1].i2c_sda	scb[1].spi_miso	P3.1, TCPWM0, SCB1
13	P3.2	E5	P3.2			tcpwm.line[1]	scb[1].uart_cts	swd_data	scb[1].spi_clk	P3.2, TCPWM1, SCB1, SWD_IO
14	P3.3	B5	P3.3			tcpwm.line_compl[1]	scb[1].uart_rts	swd_clk	scb[1].spi_select0	P3.3, TCPWM1, SCB1, SWD_CLK
15	P3.4	D4	P3.4						scb[1].spi_select1	P3.4, SCB1

Descriptions of the power pin functions are as follows:

VDDD: Power supply for the chip.

VSSD: Ground pin.

VCCD: Regulated digital supply (1.8 V ±5% if supplied externally).

Power

The supply voltage range is 1.71 to 5.5 V with all functions and circuits operating over that range.

The PSoC 4200DS family allows two distinct modes of power supply operation: Unregulated External Supply and Regulated External Supply modes.

Unregulated External Supply

In this mode, the PSoC 4200DS is powered by an External Power Supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation, for instance, the chip can be powered from a battery system that starts at 3.5V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4200DS supplies the internal logic and the VCCD output of the PSoC 4200DS must be bypassed to ground via an external capacitor.

Bypass capacitors must be used from VDDD to ground, typical practice for systems in this frequency range is to use a capacitor in the 1 µF range in parallel with a smaller capacitor (0.1 µF, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the Bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

Power Supply	Typical Bypass Capacitors
VDDD–VSS	0.1-µF ceramic at each pin plus bulk capacitor 1 to 10 µF.
VCCD–VSS	0.1-µF ceramic capacitor at the VCCD pin

Regulated External Supply

In this mode, the PSoC 4200DS is powered by an external power supply that must be within the range of 1.71 to 1.89 V (1.8 ±5%); note that this range needs to include power supply ripple. In this mode, VCCD and VDDD pins are shorted together and bypassed. The internal regulator should be disabled in firmware.

Development Support

The PSoC 4200DS family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

Documentation

A suite of documentation supports the PSoC 4200DS family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

Software User Guide: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

Component Datasheets: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

Application Notes: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

Technical Reference Manual: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers.

Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4200DS family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.

Electrical Specifications

Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings[1]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID1	V_{DD_ABS}	Analog or digital supply relative to V_{SS} ($V_{SSD} = V_{SSA}$)	–0.5	–	6	V	Absolute maximum
SID2	V_{CCD_ABS}	Direct digital core voltage input relative to V_{SSD}	–0.5	–	1.95	V	Absolute maximum
SID3	V_{GPIO_ABS}	GPIO voltage; V_{DDD} or V_{DDA}	–0.5	–	V_{DD}+0.5	V	Absolute maximum
SID4	I_{GPIO_ABS}	Current per GPIO	–25	–	25	mA	Absolute maximum
SID5	$I_{G\text{-}PIO\_injection}$	GPIO injection current per pin	–0.5	–	0.5	mA	Absolute maximum
BID44	ESD_HBM	Electrostatic discharge human body model	2200	–	–	V	
BID45	ESD_CDM	Electrostatic discharge charged device model	500	–	–	V	
BID46	LU	Pin current for latch-up	–140	–	140	mA	

Device Level Specifications

All specifications are valid for -40 °C ≤ TA ≤ 85 °C and TJ ≤ 100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 3. DC Specifications

Spec Id#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID53	V_{DDD}	Power supply input voltage unregulated	1.8	–	5.5	V	With on-chip internal regulator enabled
SID255	V_{DDD}	Power supply input voltage externally regulated	1.71	1.8	1.89	V	Externally regulated within this range
SID54	V_{CCD}	Output voltage (for core logic)	–	1.8	–	V	
SID55	C_{EFC}	External regulator voltage bypass	–	0.1	–	µF	X5R ceramic or better
SID56	C_{EXC}	Power supply decoupling capacitor	–	1	–	µF	X5R ceramic or better
Active Mode							
SID6	I_{DD1}	Execute from flash; CPU at 6 MHz	–	2.1	2.85	mA	
SID7	I_{DD2}	Execute from flash; CPU at 12 MHz	–	3.6	4	mA	
SID8	I_{DD3}	Execute from flash; CPU at 24 MHz	–	5.3	6	mA	
SID9	I_{DD4}	Execute from flash; CPU at 48 MHz	–	9.8	13	mA	
Sleep Mode							
SID21	I_{DD16}	I^2C wakeup, WDT, and comparators on. Regulator off.	–	1.45	1.65	mA	V_{DD} = 1.71 to 1.89, 6 MHz
SID22	I_{DD17}	I^2C wakeup, WDT, and comparators on.	–	1.8	2.45	mA	V_{DD} = 1.8 to 5.5, 6 MHz
SID23	I_{DD18}	I^2C wakeup, WDT, and comparators on. Regulator off.	–	1.6	1.9	mA	V_{DD} = 1.71 to 1.89, 12 MHz

Note

1. Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to absolute maximum conditions for extended periods of time may affect device reliability. The maximum storage temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below absolute maximum conditions but above normal operating conditions, the device may not operate to specification.

Table 5. GPIO DC Specifications *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID62	V_{OL}	Output voltage low level	–	–	0.6	V	I_{OL} = 8 mA at 3 V V_{DDD}
SID62A	V_{OL}	Output voltage low level	–	–	0.4	V	I_{OL} = 3 mA at 3 V V_{DDD}
SID63	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID64	$R_{PULLDOWN}$	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID65	I_{IL}	Input leakage current (absolute value)	–	–	2	nA	25 °C, V_{DDD} = 3.0 V
SID66	C_{IN}	Input capacitance	–	–	7	pF	
SID67	V_{HYSTTL}	Input hysteresis LVTTL	25	40	–	mV	$V_{DDD} \geq 2.7$ V
SID68	$V_{HYSCMOS}$	Input hysteresis CMOS	0.05 × V_{DDD}	–	–	mV	
SID69	I_{DIODE}	Current through protection diode to V_{DD}/Vss	–	–	100	µA	Guaranteed by characterization
SID69A	I_{TOT_GPIO}	Maximum Total Source or Sink Chip Current	–	–	200	mA	Guaranteed by characterization

Table 6. GPIO AC Specifications
(Guaranteed by Characterization)[3]

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T_{RISEF}	Rise time in fast strong mode	2	–	12	ns	3.3 V V_{DDD}, Cload = 25 pF
SID71	T_{FALLF}	Fall time in fast strong mode	2	–	12	ns	3.3 V V_{DDD}, Cload = 25 pF
SID72	T_{RISES}	Rise time in slow strong mode	10	–	60	ns	3.3 V V_{DDD}, Cload = 25 pF
SID73	T_{FALLS}	Fall time in slow strong mode	10	–	60	ns	3.3 V V_{DDD}, Cload = 25 pF
SID74	$F_{GPIOUT1}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Fast strong mode.	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	$F_{GPIOUT2}$	GPIO Fout;1.7 V≤ V_{DDD}≤ 3.3 V. Fast strong mode.	–	–	16.7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID76	$F_{GPIOUT3}$	GPIO Fout;3.3 V ≤ V_{DDD} ≤ 5.5 V. Slow strong mode.	–	–	7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID245	$F_{GPIOUT4}$	GPIO Fout;1.7 V ≤ V_{DDD} ≤ 3.3 V. Slow strong mode.	–	–	3.5	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID246	F_{GPIOIN}	GPIO input operating frequency; 1.71 V ≤ V_{DDD} ≤ 5.5 V	–	–	48	MHz	90/10% V_{IO}

Note
3. Simultaneous switching transitions on many fully-loaded GPIO pins may cause ground perturbations depending on several factors including PCB and decoupling capacitor design. For applications that are very sensitive to ground perturbations, the slower GPIO slew rate setting may be used.

XRES

Table 7. XRES DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	V_{IH}	Input voltage high threshold	0.7 × V_{DDD}	–	–	V	CMOS Input
SID78	V_{IL}	Input voltage low threshold	–	–	0.3 × V_{DDD}	V	CMOS Input
SID79	R_{PULLUP}	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID80	C_{IN}	Input capacitance	–	3	–	pF	
SID81	$V_{HYSXRES}$	Input voltage hysteresis	–	100	–	mV	Guaranteed by characterization
SID82	I_{DIODE}	Current through protection diode to V_{DDD}/V_{SS}	–	–	100	µA	Guaranteed by characterization

Table 8. XRES AC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83	$T_{RESETWIDTH}$	Reset pulse width	1	–	–	µs	Guaranteed by characterization

Analog Peripherals

Comparator

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID85	$V_{OFFSET2}$	Input offset voltage, Common Mode voltage range from 0 to V_{DD}-1	–	–	±4	mV	
SID86	V_{HYST}	Hysteresis when enabled, Common Mode voltage range from 0 to V_{DD} -1.	–	10	35	mV	Guaranteed by characterization
SID87	V_{ICM1}	Input common mode voltage in normal mode	0	–	V_{DDD} – 0.1	V	Modes 1 and 2.
SID247	V_{ICM2}	Input common mode voltage in low-power mode	0	–	V_{DDD}	V	
SID88	CMRR	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7$ V. Guaranteed by characterization
SID88A	CMRR	Common mode rejection ratio	42	–	–	dB	$V_{DDD} < 2.7$ V. Guaranteed by characterization
SID89	I_{CMP1}	Block current, normal mode	–	–	400	µA	Guaranteed by characterization
SID248	I_{CMP2}	Block current, low power mode	–	–	100	µA	Guaranteed by characterization
SID90	Z_{CMP}	DC input impedance of comparator	35	–	–	MΩ	Guaranteed by characterization

Table 10. Comparator AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID91	T_{RESP1}	Response time, normal mode	–	–	110	ns	50-mV overdrive
SID258	T_{RESP2}	Response time, low power mode	–	–	200	ns	50-mV overdrive

Digital Peripherals

The following specifications apply to the Timer/Counter/PWM peripheral in timer mode.

Timer/Counter/PWM

Table 11. TCPWM Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.TCPWM.1	ITCPWM1	Block current consumption at 3 MHz	–	–	45	µA	All modes (Timer/Counter/PWM)
SID.TCPWM.2	ITCPWM2	Block current consumption at 12 MHz	–	–	155	µA	All modes (Timer/Counter/PWM)
SID.TCPWM.2A	ITCPWM3	Block current consumption at 48 MHz	–	–	650	µA	All modes (Timer/Counter/PWM)
SID.TCPWM.3	TCPWMFREQ	Operating frequency	–	–	Fc	MHz	Fc max = Fcpu. Maximum = 48 MHz
SID.TCPWM.4	TPWMENEXT	Input Trigger Pulse Width for all Trigger Events	2/Fc	–	–	ns	Trigger Events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.
SID.TCPWM.5	TPWMEXT	Output Trigger Pulse widths	2/Fc	–	–	ns	Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) trigger outputs
SID.TCPWM.5A	TCRES	Resolution of Counter	1/Fc	–	–	ns	Minimum time between successive counts
SID.TCPWM.5B	PWMRES	PWM Resolution	1/Fc	–	–	ns	Minimum pulse width of PWM Output
SID.TCPWM.5C	QRES	Quadrature inputs resolution	1/Fc	–	–	ns	Minimum pulse width between Quadrature phase inputs.

I^2C

Table 12. Fixed I^2C DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID149	I_{I2C1}	Block current consumption at 100 kHz	–	–	50	µA	
SID150	I_{I2C2}	Block current consumption at 400 kHz	–	–	135	µA	
SID151	I_{I2C3}	Block current consumption at 1 Mbps	–	–	310	µA	
SID152	I_{I2C4}	I^2C enabled in Deep Sleep mode	–	–	1.4	µA	

Table 13. Fixed I^2C AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID153	F_{I2C1}	Bit rate	–	–	1	Mbps	

Table 14. Fixed UART DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I_{UART1}	Block current consumption at 100 Kbits/sec	–	–	55	µA	
SID161	I_{UART2}	Block current consumption at 1000 Kbits/sec	–	–	312	µA	

Table 15. Fixed UART AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F_{UART}	Bit rate	–	–	1	Mbps	

SPI Specifications

Table 16. Fixed SPI DC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID163	I_{SPI1}	Block current consumption at 1 Mbits/sec	–	–	360	µA	
SID164	I_{SPI2}	Block current consumption at 4 Mbits/sec	–	–	560	µA	
SID165	I_{SPI3}	Block current consumption at 8 Mbits/sec	–	–	600	µA	

Table 17. Fixed SPI AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID166	F_{SPI}	SPI operating frequency (master; 6X oversampling)	–	–	8	MHz	

Table 18. Fixed SPI Master mode AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID167	T_{DMO}	MOSI valid after Sclock driving edge	–	–	15	ns
SID168	T_{DSI}	MISO valid before Sclock capturing edge. Full clock, late MISO Sampling used	20	–	–	ns
SID169	T_{HMO}	Previous MOSI data hold time with respect to capturing edge at Slave	0	–	–	ns

Table 19. Fixed SPI Slave mode AC Specifications

(Guaranteed by Characterization)

Spec ID	Parameter	Description	Min	Typ	Max	Units
SID170	T_{DMI}	MOSI valid before Sclock capturing edge	40	–	–	ns
SID171	T_{DSO}	MISO valid after Sclock driving edge	–	–	42 + 3 × (1/FCPU)	ns
SID171A	T_{DSO_ext}	MISO valid after Sclock driving edge in Ext. Clock mode	–	–	48	ns
SID172	T_{HSO}	Previous MISO data hold time	0	–	–	ns
SID172A	$T_{SSELSCK}$	SSEL Valid to first SCK Valid edge	100	–	–	ns

Memory

Table 20. Flash DC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID173	V_{PE}	Erase and program voltage	1.71	–	5.5	V	

Table 21. Flash AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID174	$T_{ROWWRITE}$	Row (block) write time (erase and program)	–	–	20	ms	Row (block) = 256 bytes
SID175	$T_{ROWERASE}$	Row erase time	–	–	13	ms	
SID176	$T_{ROWPROGRAM}$	Row program time after erase	–	–	7	ms	
SID178	$T_{BULKERASE}$	Bulk erase time (64 KB)	–	–	35	ms	
SID180	$T_{DEVPROG}$	Total device program time	–	–	15	seconds	Guaranteed by characterization
SID181	F_{END}	Flash endurance	100 K	–	–	cycles	Guaranteed by characterization
SID182	F_{RET}	Flash retention. $T_A \leq 55$ °C, 100 K P/E cycles	20	–	–	years	Guaranteed by characterization
SID182A		Flash retention. $T_A \leq 85$ °C, 10 K P/E cycles	10	–	–	years	Guaranteed by characterization

System Resources

Power-on-Reset and Brown-out Detect (BOD) Specifications

Table 22. Power On Reset

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	–	67	V/ms	At power-up
SID185	$V_{RISEIPOR}$	Rising trip voltage	0.80	–	1.45	V	Guaranteed by characterization
SID186	$V_{FALLIPOR}$	Falling trip voltage	0.75	–	1.4	V	Guaranteed by characterization
BID51	Twupo	Initialization after Power-On	–	–	3	ms	

Table 23. Brown-out Detect (BOD) for V_{CCD}

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID190	$V_{FALLPPOR}$	BOD trip voltage in active and sleep modes	1.48	-	1.62	V	Guaranteed by characterization
SID192	$V_{FALLDPSLP}$	BOD trip voltage in Deep Sleep	1.11	-	1.5	V	Guaranteed by characterization

SWD Interface

Table 24. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWDCLK1	3.3 V ≤ V_{DD} ≤ 5.5 V	–	–	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	1.71 V ≤ V_{DD} ≤ 3.3 V	–	–	7	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	–	–	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	T = 1/f SWDCLK	–	–	0.5*T	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	T = 1/f SWDCLK	1	–	–	ns	Guaranteed by characterization

Internal Main Oscillator

Table 25. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I_{IMO1}	IMO operating current at 48 MHz	–	–	250	µA	
SID219	I_{IMO2}	IMO operating current at 24 MHz	–	–	180	µA	

Table 26. IMO AC Specifications

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	$F_{IMOTOL1}$	Frequency variation	–	–	±2	%	
SID226	$T_{STARTIMO}$	IMO startup time	–	–	7	µs	
SID228	$T_{JITRMSIMO2}$	RMS Jitter at 24 MHz	–	145	–	ps	

Internal Low-Speed Oscillator

Table 27. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I_{ILO1}	ILO operating current	–	0.3	1.05	µA	Guaranteed by Characterization

Ordering Information

The PSoC 4200DS family part numbers and features are listed in the following table.

Table 32. PSoC 4200DS Ordering Information

Category	Marketing Part Number (MPN)	MAX. CPU Speed (MHz)	No. of DMA Channels	Flash (KB)	SRAM (KB)	Low-power Comparators	No. of Universal Digital Blocks (UDB)	Timer/Counter/PWM Blocks (TCPWM)	No. of Serial Communication Blocks (SCB)	PRGIO	No. of GPIOs	Package Type
4045	CY8C4045PVI-DS402	48	8	32	4	2	-	4	3	1	21	28-pin SSOP
	CY8C4045FNI-DS402	48	8	32	4	2	-	4	3	1	21	25-ball WLCSP
4245	CY8C4245PVI-DS402	48	8	32	4	2	4	4	3	1	21	28-pin SSOP
	CY8C4245FNI-DS402	48	8	32	4	2	4	4	3	1	21	25-ball WLCSP
4246	CY8C4246PVI-DS402	48	8	64	8	2	4	4	3	1	21	28-pin SSOP
	CY8C4246FNI-DS402	48	8	64	8	2	4	4	3	1	21	25-ball WLCSP

The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
A	Family	2	4200 Family
B	CPU Speed	4	48 MHz
C	Flash Capacity	5	32 KB
		6	64 KB
DE	Package Code	PV	SSOP
		FN	CSP
F	Temperature Range	I	Industrial
S	Silicon Family	D	PSoC 4D
XYZ	Attributes Code	000-999	Code of feature set in the specific family

Part Numbering Conventions

The part number fields are defined as follows.

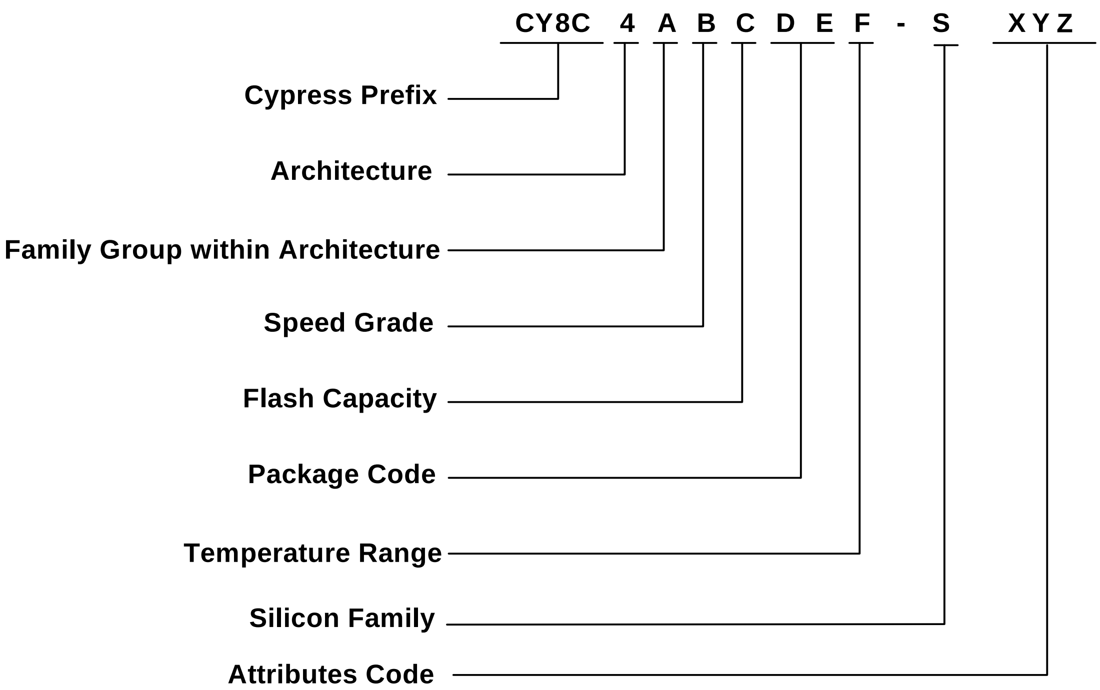


Figure 5. 28-Pin SSOP Package Outline

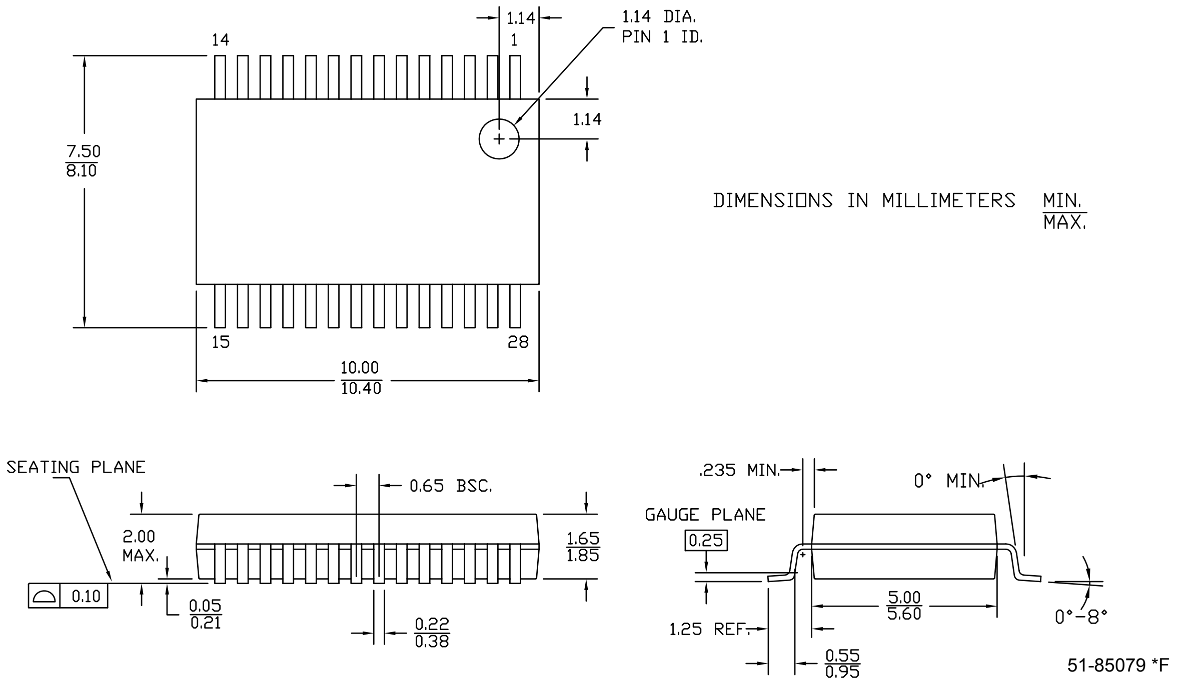


Figure 6. 25-ball CSP 2.07 × 2.11 × 0.55 mm

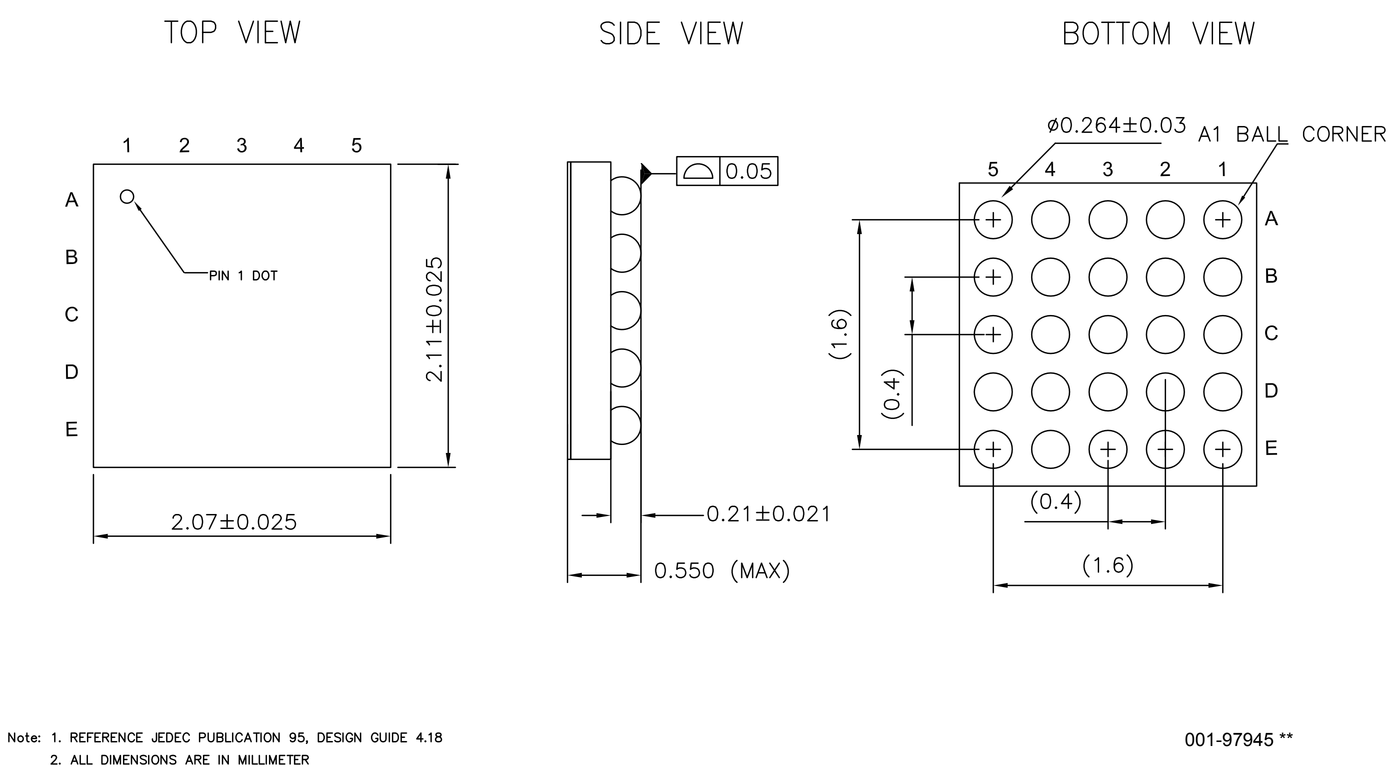


Table 36. Acronyms Used in this Document *(continued)*

Acronym	Description
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I^2C serial clock
SDA	I^2C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol
SWV	single-wire viewer
TD	transaction descriptor, see also DMA

Table 36. Acronyms Used in this Document *(continued)*

Acronym	Description
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

Document Conventions

Units of Measure

Table 37. Units of Measure

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
µA	microampere
µF	microfarad
µH	microhenry
µs	microsecond
µV	microvolt
µW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

Revision History

Description Title: PSoC® 4: PSoC 4200DS Family Datasheet Programmable System-on-Chip (PSoC®) Document Number: 001-98044				
Revision	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
**	4795389	WKA	06/23/2015	New datasheet
*A	4931127	WKA	09/23/2015	Removed 28-pin SSOP package. Updated Pinouts. Updated DC Specifications. Removed SID85A, SID247A, SID259, and SID92. Added BID51.
*B	4958966	WKA	10/12/2015	Updated package dimensions. Updated bulk erase time to 64 KB. Changed SID226 max to 7. Updated T_{JA} typ to 48 and T_{JC} typ to 0.47.
*C	5759255	WKA	05/31/2017	Added 28-pin SSOP package. Updated to new template.
*D	5825921	WKA	07/20/2017	Updated Document Title to read as "PSoC® 4: PSoC 4200DS Family Datasheet Programmable System-on-Chip (PSoC®)". Replaced "PSoC 4200D" with "PSoC 4200DS" in all instances across the document.